CLAIMS

1. A flexible printed wiring board comprising a first flexible printed wiring part having metal bumps and a second flexible printed wiring part having connection pads, the metal bumps and the connection pads being connected to each other, wherein the first flexible printed wiring part comprises a conductive layer and an insulating layer adjacent thereto; holes are provided in the insulating layer so as to reach the conductive layer; metal plugs are formed in said holes by an electrolytic plating method; and the tips of the metal plugs constitute the metal bumps that project from the insulating layer.

2. The flexible printed wiring board according to claim 1, wherein the insulating layer is a polyimide layer and the metal plugs are electrolytic copper plating plugs.

3. The flexible printed wiring board according to claim 2, wherein the insulating layer is obtained by imidizing polyamic acid.

Subj 4 7

4. The flexible printed wiring board according to any of claims 1 to 3, wherein the metal bumps of the first flexible printed wiring part and the connection pads of the

Sub #7

second flexible printed wiring part are arranged in a zigzag fashion.

5. The flexible printed wiring board according to any of claims 1 to 4, wherein the first flexible printed wiring part and the second flexible printed wiring part are stuck together by an anisotropic conductive film, thermoplastic polyimide, or epoxy resin.

6. A method of manufacturing a flexible printed wiring board according to claim 1, comprising:

(a) a step of creating first flexible printed wiring parts and/or second flexible printed wiring parts in a laminated sheet for flexible printed wiring composed of a conductive layer and an insulating layer formed adjacent thereto, such that as many as possible first flexible printed wiring parts and/or second flexible printed wiring parts can be obtained per unit area of the laminated sheet;

in which the metal bumps of the first flexible printed wiring parts are created by forming holes in the insulating layer adjacent to the conductive layer, so as to reach the conductive layer, by chemical etching using a photolithographic method, then, while forming metal plugs in the holes of the insulating layer by an electrolytic plating method in which the conductive layer is used as the

cathode, further continuously growing these metal plugs by an electrolytic plating method so that the tips thereof project from the surface of the insulating layer;

(b) a step of obtaining the first flexible printed wiring parts and the second flexible printed wiring parts from the laminated sheet for flexible printed wiring by cutting the same; and

(c) a step of sticking together the first flexible printed wiring parts and the second flexible printed wiring parts that have thus been obtained while ensuring conduction between the metal bumps of the first flexible printed wiring parts and the connection pads of the second flexible printed wiring parts.

Add A27